

[illegible]

(a) preparing a plurality of steel plates and coppers in a clean working room, and a plurality of prepregs and cores in a working room;

(c) conveying the sandwiched lamination board to the working room, and laminating the sandwiched lamination board, the prepregs, and the cores serially, thereby forming a multi-layer board.

3. The pin lamination method that may eliminate pits and dents formed in a multi-layer printed wiring board in accordance with claim 2, wherein in the step (b), the ply-up device is provided with multiple pins, and the pin holes of the coppers and the steel plate align with the pins of the ply-up device, thereby facilitating insertion of the pins of the ply-up device.

1 4. The pin lamination method that may eliminate pits and dents
2 formed in a multi-layer printed wiring board in accordance with claim 1,
3 wherein in the step (c), the sandwiched lamination board, the prepregs, and the
4 cores are mounted between two mold plates provided in the working room.

5 5. The pin lamination method that may eliminate pits and dents
6 formed in a multi-layer printed wiring board in accordance with claim 4,
7 wherein each of the two mold plates is provided with multiple pins, and pin
8 holes of the sandwiched lamination board, the prepregs, and the cores align
9 with the pins of the mold plates, thereby facilitating insertion of the pins of the
10 mold plates.

11 6. A ply-up device for performing the pin lamination method that
12 may eliminate pits and dents formed in a multi-layer printed wiring board in
13 accordance with claim 1, wherein the ply-up device includes a work table, a lift
14 rod, an inclined board, a base steel plate, and a ply-up plate, wherein:

15 the lift rod has a first end pivoted on a first side of the work table, and
16 a second end pivoted with a first end of the inclined board which has a second
17 end pivoted on a second side of the work table, the lift rod may be lifted and
18 lowered for adjusting the inclined angle of the inclined board;

19 the base steel plate is secured on the inclined board; and

20 the ply-up plate is secured on the base steel plate.

21 7. The ply-up device in accordance with claim 6, wherein the base
22 steel plate includes multiple L-shaped fixing blocks secured on the inclined
23 board, and is provided with multiple pin holes for insertion of multiple pins.

1 8. The ply-up device in accordance with claim 7, wherein the ply-up
2 plate includes multiple pads secured on the fixing blocks, and is provided with
3 multiple pin holes for insertion of the multiple pins.

4 9. The ply-up device in accordance with claim 6, wherein the ply-up
5 plate has a periphery formed with multiple openings for insertion of holders.
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